

04R-00225-1.0

169-Pin FineLine Ball-Grid Array (FBGA) - Wire Bond - A:1.55

- All dimensions and tolerances conform to ASME Y14.5M 1994.
- Controlling dimension is in millimeters.
- Pin A1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

Package Information		
Description	Specification	
Ordering Code Reference	F	
Package Acronym	FBGA	
Substrate Material	BT	
Solder ball composition	Regular: 63Sn:37Pb (Typ.) Pb-free: Sn:3Ag:0.5Cu (Typ.)	
JEDEC Outline Reference	MO-192 Variation: DBE-1	
Lead Coplanarity	0.005 inch (0.12 mm)	
Weight	0.66 g (Typ.)	
Moisture Sensitivity Level	Printed on moisture barrier bag	

Symbol —	Millimeters		
	Min.	Nom.	Max.
Α	1.25	1.40	1.55
A1	0.30	0.40	0.50
A2	0.75	1.00	1.25
A3	0.65	0.70	0.75
D	14.00 BSC		
E	14.00 BSC		
b	0.45	0.50	0.55
е	1.00 BSC		

2

3 1

4

5

Pin A1

Corner

А

С

Е

G

J

L

Ν

- e

В

D

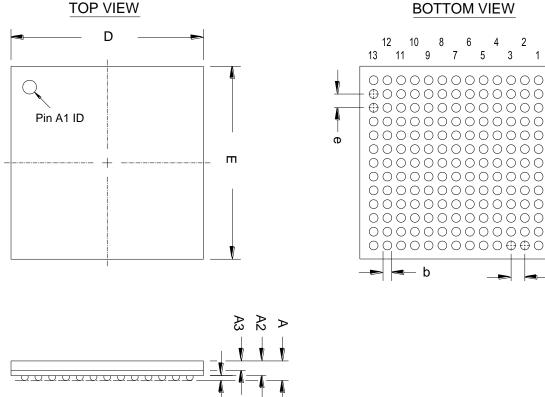
F

Н

Κ

М

Package Outline



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Document Revision History

Table 1 shows the revision history for this document.

Table 1. Document Revision History

Date	Version	Changes
June 2011	1.0	Initial release



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